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## Press Release

### LOPEC 2019 in Munich

## Smart Packaging: Printed Electronics as Growth Driver

**When pharmaceutical packages sound an alarm or food cartons measure the temperature, printed electronics are involved. LOPEC, the International Exhibition and Conference for the Printed Electronics Industry in Munich, will provide information about next generation packaging from March 19 to 21, 2019.**

Who says it is merely a cardboard box? Printed circuits, displays and the like let packages become truly multi-talented. “Since printed electronics are thin, lightweight, flexible and yet robust, they can be integrated very well into packaging, either during production or as an affixed e-label,” explains Dr. Klaus Hecker, Managing Director of the OE-A (Organic and Printed Electronics Association), a working group within the VDMA, the co-organizer of LOPEC.

Packaging with integrated electronics opens up new communication channels because it links the real world with the digital world. For instance in healthcare: Prototypes of drug packages with integrated e-paper display already exist. That way, using apps and Bluetooth, doctors can notify their patients of their individual dosages and easily adjust those if their state of health changes. “Printed electronics is becoming increasingly important in personalized medicine,” says Hecker.

The pressure to optimize costs is driving smart pharmaceutical packaging. About one fifth of all patients do not take their medication correctly—leading to expensive consequences such as antibiotic resistance or follow-up treatments. Blister packs with integrated clocks and circuits that register tablet removal are supposed to solve that problem: In case the intake is forgotten, the package flashes, emits an alarm or sends a reminder message. Smart packaging is already being used in clinical studies in which drug manufacturers test new drug substances on thousands of subjects, thus helping to reduce costs.

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Packaging with built-in temperature and humidity sensors on the other hand can monitor the correct storage of drugs. Sensor technology is also of interest for food and other sensitive goods. In any case, smart packaging is a cross-sector trend. Near-field communication, NFC for short, plays a key role here, and is widely known from metro tickets, ski passes and more recently also from contactless payment by mobile phone. Packaging with NFC chips brings a breath of fresh air into marketing, because they connect brand products directly with the customer. Product information, videos and much more are sent to the consumer's smartphone as soon as it is held close to the packaging. As a seal of authenticity, NFC tags also protect perfumes, wine and other luxury goods against counterfeiting.

The global market for smart packaging is developing faster than anticipated and is expected to reach a volume of over 48 billion US dollars in 2024. "Printed electronics is making a significant contribution to this growth," emphasizes Hecker. "We are thrilled that LOPEC 2019 will once again cover the entire value chain of printed electronics, from materials development to plant construction to the end product." With its extensive exhibition and conference program, LOPEC is not only targeting insiders but also representatives of all sectors and industries that want to increase their competitiveness with the aid of printed electronics.

### **Service**

Further information and background data can be found at [www.lopec.com](http://www.lopec.com). Image material is available from the [media database](#). All contributions from LOPEC TV can be found on our [webpage](#) as well as in the [media library](#). In the [download section](#), original recordings from LOPEC in broadcast quality are made available to you free of charge.

### **LOPEC**

LOPEC (Large-area, Organic & Printed Electronics Convention) is the leading international event for printed electronics. The combination of an exhibition and a conference is the perfect way to depict the complex and dynamic nature of this young industry. Around 2,500 participants from 51 countries attended the event in 2018. There were 153 exhibitors from 21 countries, and 188 conference presentations from 25 countries. LOPEC is organized jointly by the OE-A (Organic and Printed Electronics Association) and Messe München GmbH. The next event takes place from March 19 to 21, 2019 at the ICM – Internationales Congress Center München in Munich, Germany. [www.lopec.com](http://www.lopec.com)

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**Messe München**

Messe München is one of the leading exhibition organizers worldwide with more than 50 of its own trade shows for capital goods, consumer goods and new technologies. Every year, a total of over 50,000 exhibitors and around three million visitors take part in more than 200 events at the exhibition center in Munich, at the ICM – Internationales Congress Center München and the MOC Veranstaltungszentrum München as well as abroad. Together with its subsidiary companies, Messe München organizes trade shows in China, India, Brazil, Russia, Turkey, South Africa, Nigeria, Vietnam and Iran. With a network of associated companies in Europe, Asia, Africa and South America as well as around 70 representations abroad for over 100 countries, Messe München has a global presence.

**OE-A**

The OE-A (Organic and Printed Electronics Association) was founded in December 2004 and is the leading international industry association for organic and printed electronics. The OE-A represents the entire value chain of this industry. The members are world-class global companies and institutions, ranging from R&D institutes, mechanical engineering companies and material suppliers to producers and end-users. Well over 200 companies from Europe, Asia, North America, South America, Africa and Oceania are working together to promote the establishment of a competitive production infrastructure for organic and printed electronics. The OE-A is building a bridge between science, technology and application. The OE-A is a working group within VDMA.  
[www.oe-a.org](http://www.oe-a.org)